

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Decommission of Newport, Wales wafer fab, as announced on May 5th 2015

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **05-July-2017**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

Decommission of Newport, Wales wafer fab, as announced on May 5th 2015

► **Products affected:**

See attached for affected parts.

► **Detailed Change Information:**

Subject: Wafer Fab Site.

Reason: The wafer production of the affected products will be transferred to Dresden, Germany according to the global Infineon production strategy.

Description: Decommission of Newport, Wales wafer fab, as announced on May 5th 2015

Add Dresden 300MM as qualified Fab for Gen 10.7

	OLD	NEW
Wafer Fab Location	Vanguard International Semiconductor or Infineon Technologies Newport Limited	Infineon Technologies AG, Dresden, Germany or Vanguard International Semiconductor

► **Product Identification:** Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► **Impact of Change:** No changes to form, fit, or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► **Attachments:** 1164-DISTI42-C4048408-AffectedParts.xlsx

► **Time Schedule:**

- **Final qualification report:** Available
- **First samples available:** On request
- **Intended start of delivery:** 17-July-2017

If you have any questions, please do not hesitate to contact your local Sales office.